

## DECLARATION FOR PATENT APPLICATION

ATTY DOCKET NO. \_\_\_\_\_

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled: **MULTI-LEVEL CIRCUIT SUBSTRATE, METHOD FOR MANUFACTURING SAME AND METHOD FOR ADJUSTING A CHARACTERISTIC IMPEDANCE THEREFOR**  
the specification of which: (check one)

☒ is attached hereto.

was filed on \_\_\_\_\_ 19\_\_\_\_, as U.S. or PCT International Application No. \_\_\_\_\_, and was amended on \_\_\_\_\_ 19\_\_\_\_ (if applicable).

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.  
I acknowledge the duty to disclose information that is material to patentability as defined in 37 CFR § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or under § 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below; and have also identified below, by checking the "No" box, any foreign application for patent or inventor's certificate or any PCT international application having a filing date before that of the application on which priority is claimed.

Priority Claimed:

Foreign (or PCT International) Application No.	Country	Foreign (or PCT International) Filing Date	Yes	No
P 10-295132	Japan	October 16, 1998	X	
P 11-282505	Japan	October 4, 1999	X	

The following foreign application(s), if any, were filed more than 12 months (6 months for designs) before this U.S. application:

Foreign Application No.	Country	Foreign Filing Date

I hereby claim the benefit under 35 U.S.C. § 119(e) of any U.S. provisional application(s) that may be listed below.

U.S. Provisional Application No.	Filing Date

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s) or under § 365(c) of any PCT international application(s) designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior U.S. or PCT international application in the manner provided by 35 U.S.C. § 112, ¶ 1, I acknowledge the duty to disclose information that is material to patentability as defined in 37 CFR § 1.56 that became available between the filing date of the prior application and the national or PCT international filing date of this application.

U.S. (or PCT) Parent Application No.	U.S. (or PCT) Parent Filing Date	Status (patented, pending, abandoned)

I hereby appoint the practitioners associated with CUSTOMER NUMBER 20,121 as having Power of Attorney to prosecute this application and transact all related business before the USPTO, and I direct that all correspondence be sent to the address associated with that Customer Number.

Direct Telephone Calls to:

Voice: (202) 508-4000 Thelen Reid & Priest FAX: (202) 508-4321  
FAX: (202) 508-4395 for patent & trademark matters only

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor	Hideki IWAKI
Inventor's Signature:	✓ <i>Hideki Iwaki</i> Date: ✓ October 1, 1999.
Residence Address:	Osaka, Japan
Country of Citizenship:	Japan
Post Office Address:	4-5, Hoshimicho, Ibaraki-shi, Osaka 567-0843

JAPAN

Additional inventors are named on attached supplemental sheet(s).

## DECLARATION FOR PATENT APPLICATION

PAGE TWO

Full name of second inventor: Yutaka TAGUCHI

Inventor's Signature: ✓ *Yutaka Taguchi*

Date: ✓ October 1, 1999.

Residence Address: Osaka, Japan

Country of Citizenship: Japan

Post Office Address: 33-3, Nishimachi, Takatsuki-shi, Osaka 569-0854

JAPAN

Full name of third inventor: Tetsuyoshi OGURA

Inventor's Signature: ✓ *Tetsuyoshi Ogura*

Date: ✓ October 1, 1999.

Residence Address: Osaka, Japan

Country of Citizenship: Japan

Post Office Address: 14-25-101, Hitotsuya 1-chome, Settsu-shi, Osaka  
566-0043 JAPAN

Full name of fourth inventor:

Inventor's Signature: ✓

Date: ✓

Residence Address:

Country of Citizenship:

Post Office Address:

Full name of fifth inventor:

Inventor's Signature: ✓

Date: ✓

Residence Address:

Country of Citizenship:

Post Office Address:

Full name of sixth inventor:

Inventor's Signature: ✓

Date: ✓

Residence Address:

Country of Citizenship:

Post Office Address:

Full name of seventh inventor:

Inventor's Signature: ✓

Date: ✓

Residence Address:

Country of Citizenship:

Post Office Address:

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UNITED STATES DEPARTMENT OF COMMERCE  
Patent and Trademark Office  
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JANUARY 21, 2000

PTAS

THEIEN REID & PRIEST LLP  
701 PA. AVE. NW.  
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UNITED STATES PATENT AND TRADEMARK OFFICE  
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PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 10/14/1999

REEL/FRAME: 010329/0099  
NUMBER OF PAGES: 2

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:  
IWAKI, HIDEKI

DOC DATE: 10/01/1999

ASSIGNOR:  
TAGUCHI, YUTAKA

DOC DATE: 10/01/1999

ASSIGNOR:  
OGURA, TETSUYOSHI

DOC DATE: 10/01/1999

ASSIGNEE:  
MATSUSHITA ELECTRIC INDUSTRIAL  
CO., LTD.  
1006, OAZA KADOMA  
OSAKA 571-8501, JAPAN

SERIAL NUMBER: 09417662  
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FILING DATE: 10/14/1999  
ISSUE DATE:

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JAN 27 2000

THEIEN REID & PRIEST LLP

010329/0099 PAGE 2

STEVEN POST, EXAMINER  
ASSIGNMENT DIVISION  
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-10-27-1999



RECOF

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SHEET -- PATENTS ONLY

ment(s) or copy(ies) thereof

Name(s) of CONVEYING Party or Parties:

Hideki IWAKI  
Yutaka TAGUCHI  
Tetsuyoshi OGURA

Name(s), Address(es) of RECEIVING Party (Parties):

Matsushita Electric Industrial Co., Ltd.  
1006, Oaza Kadoma  
Kadoma-shi  
Osaka 571-8501 JAPAN

Enter "X" if additional names are attached.

Enter "X" if additional names are attached.

DOCUMENT EXECUTION DATE(S): October 1, 1999

NATURE OF CONVEYANCE:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other:

If document is being filed with a new application, EXECUTION DATE(S) OF DECLARATION: Oct. 1, 1999

Patent Application Number(s):

Patent Number(s):

09/417662

Enter "X" if additional application numbers or patent numbers are attached.

Mail correspondence concerning this document to:

Number of Applications/Patents Involved: 1

Total fee (37 CFR § 1.21(h)): \$ 40

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STATEMENT AND SIGNATURE: *To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.*

Attorney Docket: 19228.042

Signature: ✓

*Nathaniel A. Humphries*

Date: ✓

*14 Oct 99*

Name of Person Signing: Nathaniel A. Humphries

Number of pages submitted (incl. cover sheet): 2

Commissioner of Patents and Trademarks, BOX ASSIGNMENTS, Washington, D.C. 20231

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# ASSIGNMENT OF UNITED STATES APPLICATION FOR PATENT

Whereas the undersigned, (1) Hideki IWAKI, (2) Yutaka TAGUCHI,  
(3) Tetsuyoshi OGURA, have invented certain  
improvements in MULTI-LEVEL CIRCUIT SUBSTRATE, METHOD FOR MANUFACTURING SAME  
AND METHOD FOR ADJUSTING A CHARACTERISTIC IMPEDANCE THEREFOR for which an application for Letters  
Patent of the United States of America:

<input type="checkbox"/>	was executed on even date herewith
<input type="checkbox"/>	was filed on _____ and was assigned Application No. _____

Whereas, Matsushita Electric Industrial Co., Ltd. (hereinafter referred to as Assignee) a corporation of \_\_\_\_\_ and having an address 1006, Oaza Kadoma, Kadoma-shi, OSAKA 571-8501 JAPAN, is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned by these presents, hereby assign, sell and transfer unto the said Assignee, for the territory of the United States of America and throughout the world, all right, title and interest in and to said invention and application, and any and all divisions or continuations thereof, and in and to any Letters Patent that may be granted therefor together with any reissues, extensions or renewals thereof, the same to be held and enjoyed by the Assignee for Assignee's own use and behoof, and for Assignee's legal representatives, successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by the undersigned had this Assignment and same not been made; and the undersigned, and legal representatives thereof, hereby covenant and agree to execute and deliver any and all papers, and do all lawful acts that said Assignee may consider necessary or advisable to perfect title to said invention and to obtain Letters Patent therefor, and any divisions, continuations, reissues, extensions and renewals thereof, and agree at any time upon request, to communicate to said Assignee, Assignee's successors and assigns, such facts relating to said invention and Letters Patent or the history thereof as may be known to the undersigned and testify as to the same in any interferences, opposition or other litigation, when requested to do so, all without further consideration than that now paid, but at the expense of the said Assignee, Assignee's successors or assigns.

We authorize our attorneys at THELEN REID & PRIEST L.L.P. to insert herein any identifying information concerning this patent application, such as its title, filing date and application number:

<u>Hideki Iwaki</u>	<u>October 1, 1999.</u>
First Inventor	Date
<u>Yutaka Taguchi</u>	<u>October 1, 1999.</u>
Second Inventor	Date
<u>Tetsuyoshi Ogura</u>	<u>October 1, 1999.</u>
Third Inventor	Date

THELEN REID & PRIEST L.L.P.  
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